

Title (en)

Assembly and method for pre-heating circuit boards for thermoforming

Title (de)

Anlage und Verfahren zum Vorwärmen von Platinen beim Warmumformen

Title (fr)

Installation et procédé de préchauffage de platines lors de déformations à chaud

Publication

EP 2615396 A1 20130717 (EN)

Application

EP 12008168 A 20121206

Priority

- DE 102011120681 A 20111208
- EP 12002748 A 20120419
- EP 12008168 A 20121206

Abstract (en)

The invention relates to a plant (10) for hot forming blanks (P), comprising at least one preheating device (2) and at least one main heating device (4), which is arranged downstream from the at least one preheating device (2). The preheating device (2) encompasses at least one, in particular pre-mixing, burner, which is embodied as hydrogen-oxygen burner, fuel gas-oxygen burner or acetylene burner.

IPC 8 full level

F27B 9/02 (2006.01); **B21J 1/06** (2006.01); **C21D 9/00** (2006.01); **C21D 9/46** (2006.01); **C21D 9/48** (2006.01); **F27B 9/14** (2006.01); **F27B 9/24** (2006.01); **F27B 9/36** (2006.01)

CPC (source: EP)

C21D 1/34 (2013.01); **C21D 1/52** (2013.01); **C21D 1/673** (2013.01); **C21D 9/005** (2013.01); **C21D 9/0068** (2013.01); **F27B 9/02** (2013.01); **F27B 9/028** (2013.01); **F27B 9/142** (2013.01); **F27B 9/243** (2013.01); **C21D 9/46** (2013.01)

Citation (applicant)

DE 10354411 A1 20050623 - LINDE AG [DE]

Citation (search report)

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 2615396 A1 20130717

DOCDB simple family (application)

EP 12008168 A 20121206